

MODEL: HSB45-383818 | **DESCRIPTION:** HEAT SINK

FEATURES

- BGA design
- pin fins
- copper
- clean finish



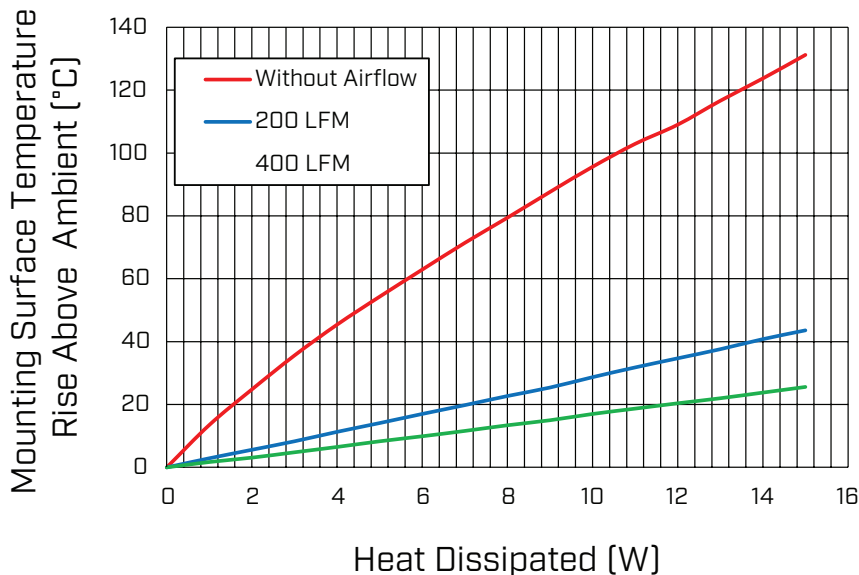
MODEL

	thermal resistance ¹				power dissipation ¹ @ 75°C ΔT, nat conv [W]
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	@ 1 W, 400 LFM [°C/W]	
HSB45-383818	10.05	13.5	2.9	1.7	7.46

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	13.5	2.9	1.7
2	24.8	5.6	3.1
3	35.6	8.3	4.8
4	45.4	11.3	6.5
5	54.3	14.1	8.3
6	62.9	17.0	9.9
7	71.4	19.8	11.6
8	79.4	22.7	13.4
9	87.6	25.4	15.0
10	95.6	28.7	17.0
11	102.9	31.8	18.7
12	109.0	34.7	20.4
13	116.6	37.6	22.0
14	123.7	40.8	23.8
15	131.2	43.6	25.6

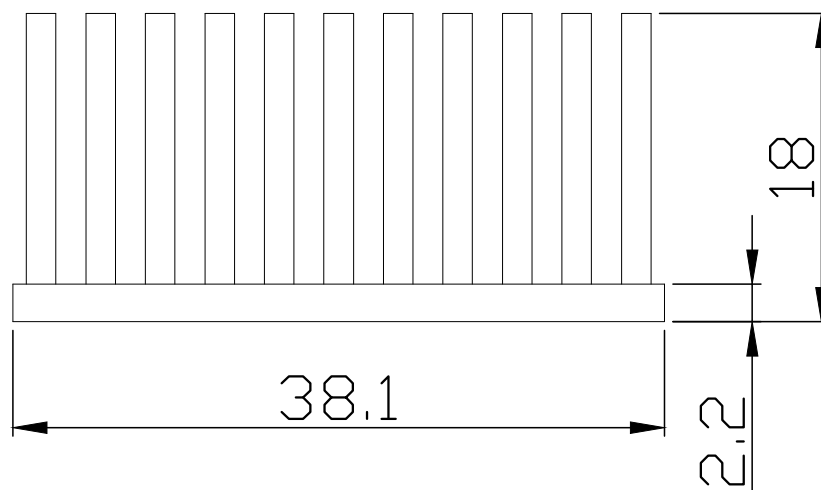
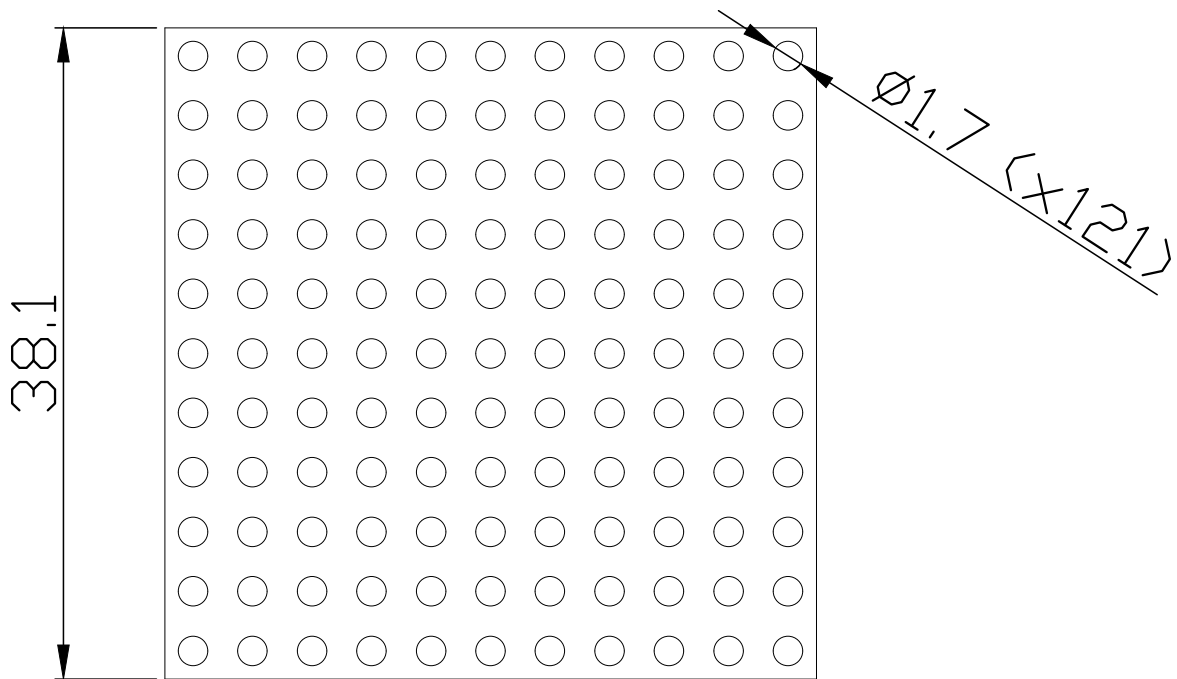


T_{hs}: "hot spot" temperature measured on the heatsink
T_a: ambient temperature

MECHANICAL DRAWING

units: mm
tolerance: ± 0.50 mm

MATERIAL	copper
FINISH	clean
WEIGHT	72 g



REVISION HISTORY

rev.	description	date
1.0	initial release	03/01/2024

The revision history provided is for informational purposes only and is believed to be accurate.



CUI Devices offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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